



FQA8N100C

N-Channel QFET[®] MOSFET

1000 V, 8 A, 1.45 Ω

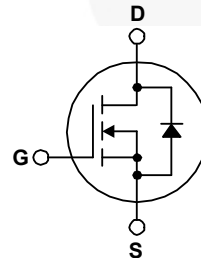
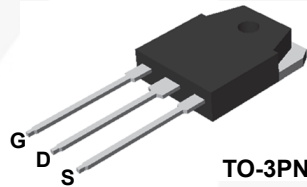
Features

- $R_{DS(on)} = 1.45 \Omega$ (Max.) @ $V_{GS} = 10 V, I_D = 4 A$
- Low Gate Charge (Typ. 53 nC)
- Low C_{rss} (Typ. 16 pF)
- 100% Avalanche Tested

Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies.



Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted.

Symbol	Parameter	FQA8N100C	Unit
V_{DSS}	Drain-Source Voltage	1000	V
I_D	Drain Current	- Continuous ($T_C = 25^\circ C$)	8
		- Continuous ($T_C = 100^\circ C$)	5
I_{DM}	Drain Current - Pulsed (Note 1)	32	A
V_{GSS}	Gate-Source voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	850	mJ
I_{AR}	Avalanche Current (Note 1)	8	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	22.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.0	V/ns
P_D	Power Dissipation ($T_C = 25^\circ C$)	- Derate above $25^\circ C$	225
			1.79
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ C$

Thermal Characteristics

Symbol	Parameter	FQA8N100C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.56	$^\circ C/W$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.24	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	$^\circ C/W$

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA8N100C	FQA8N100C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	1000	--	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	--	1.4	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 1000V, V _{GS} = 0V V _{DS} = 800V, T _C = 125°C	--	--	10 100	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	3.0	--	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 4A	--	1.2	1.45	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50V, I _D = 4A	--	8.0	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	2475	3220	pF
C _{oss}	Output Capacitance		--	195	255	pF
C _{rss}	Reverse Transfer Capacitance		--	16	24	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 500V, I _D = 8A R _G = 25Ω	--	50	110	ns
t _r	Turn-On Rise Time		--	95	200	ns
t _{d(off)}	Turn-Off Delay Time		--	122	254	ns
t _f	Turn-Off Fall Time		(Note 4)	--	80	170
Q _g	Total Gate Charge	V _{DS} = 800V, I _D = 8A V _{GS} = 10V	--	53	70	nC
Q _{gs}	Gate-Source Charge		--	13	--	nC
Q _{gd}	Gate-Drain Charge		(Note 4)	--	23	--
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	8	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	32	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 8A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 8A di/dt = 100A/μs	--	620	--	ns
Q _{rr}	Reverse Recovery Charge		--	5.2	--	μC

NOTES:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. L = 25 mH, I_{AS} = 8 A, V_{DD} = 50 V, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 8 A, di/dt ≤ 200 A/μs, V_{DD} ≤ BV_{DSS}, starting T_J = 25°C.
4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

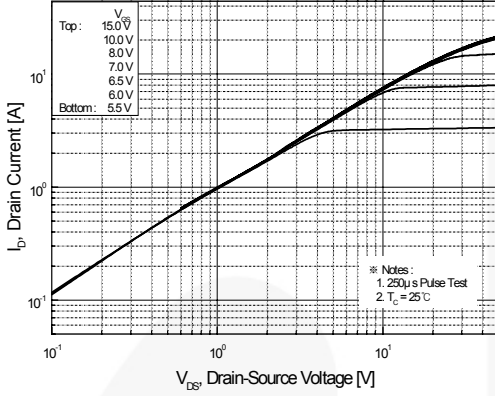


Figure 2. Transfer Characteristics

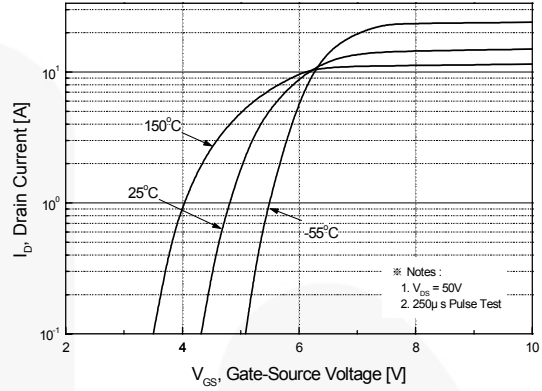


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

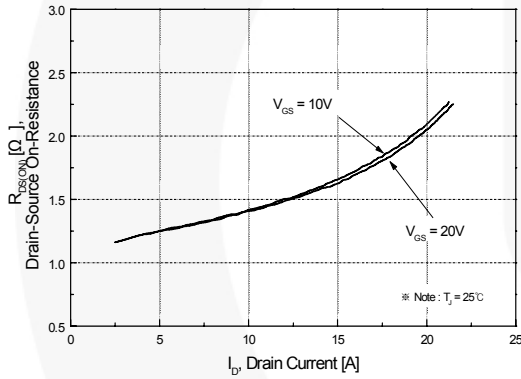


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

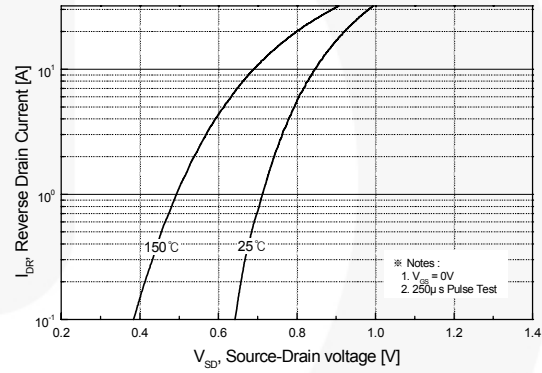


Figure 5. Capacitance Characteristics

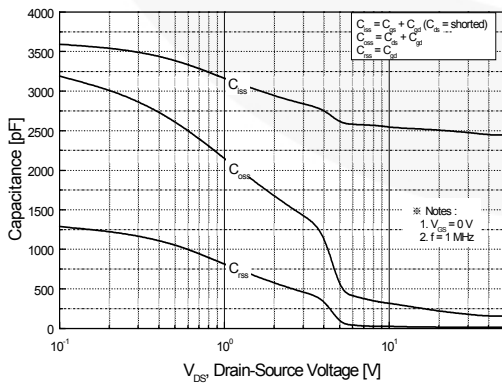
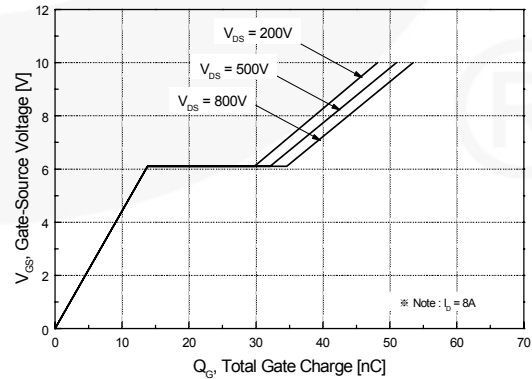


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

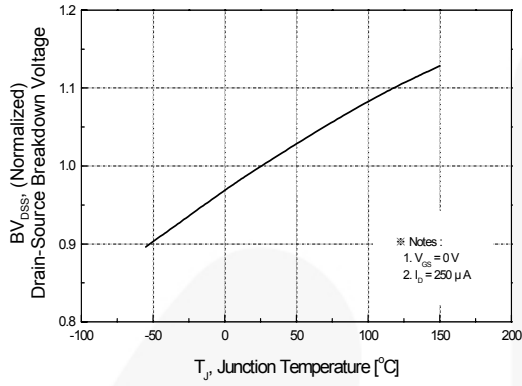


Figure 8. On-Resistance Variation vs. Temperature

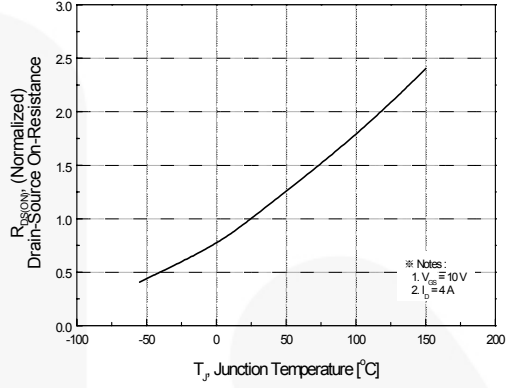


Figure 9. Maximum Safe Operating Area

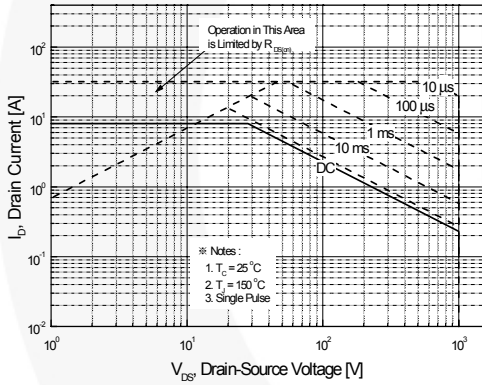


Figure 10. Maximum Drain Current vs. Case Temperature

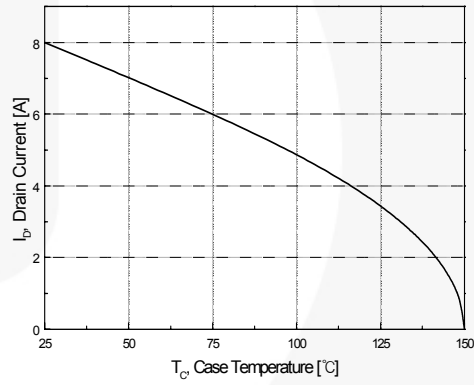
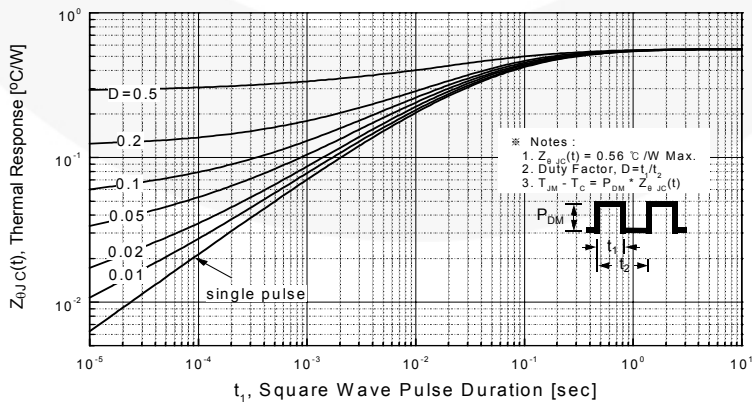


Figure 11. Transient Thermal Response Curve



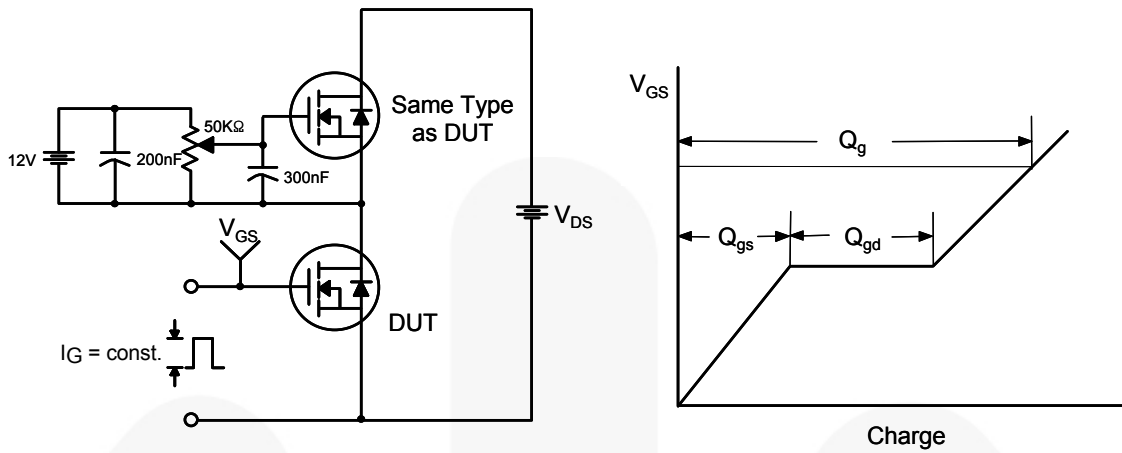


Figure 12. Gate Charge Test Circuit & Waveform

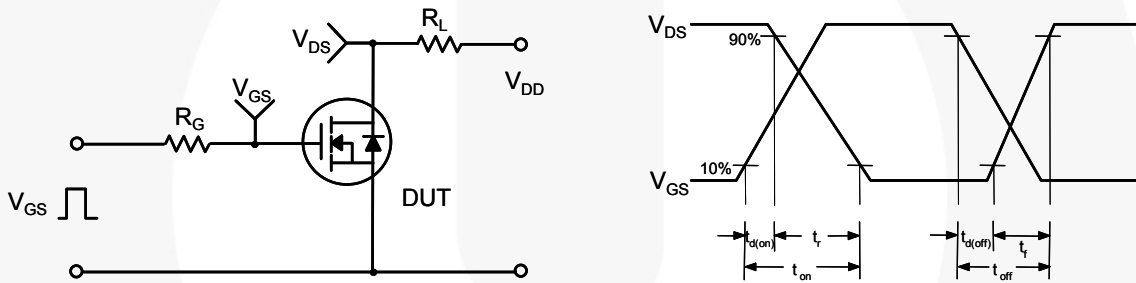


Figure 13. Resistive Switching Test Circuit & Waveforms

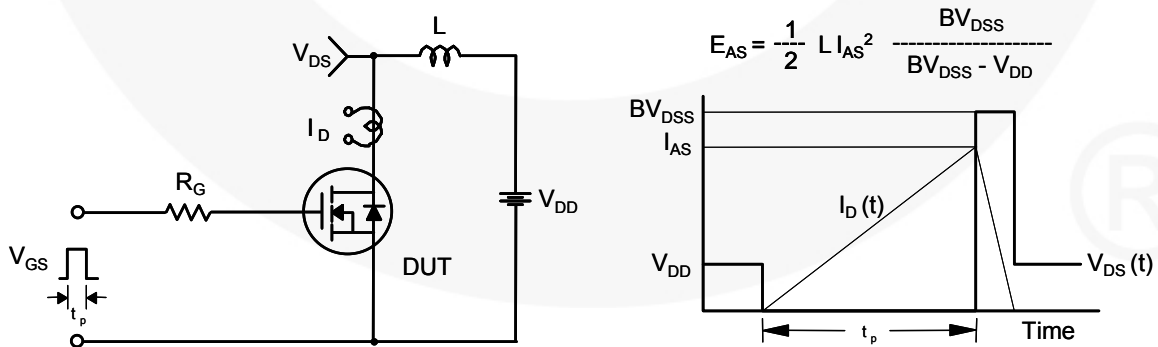


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

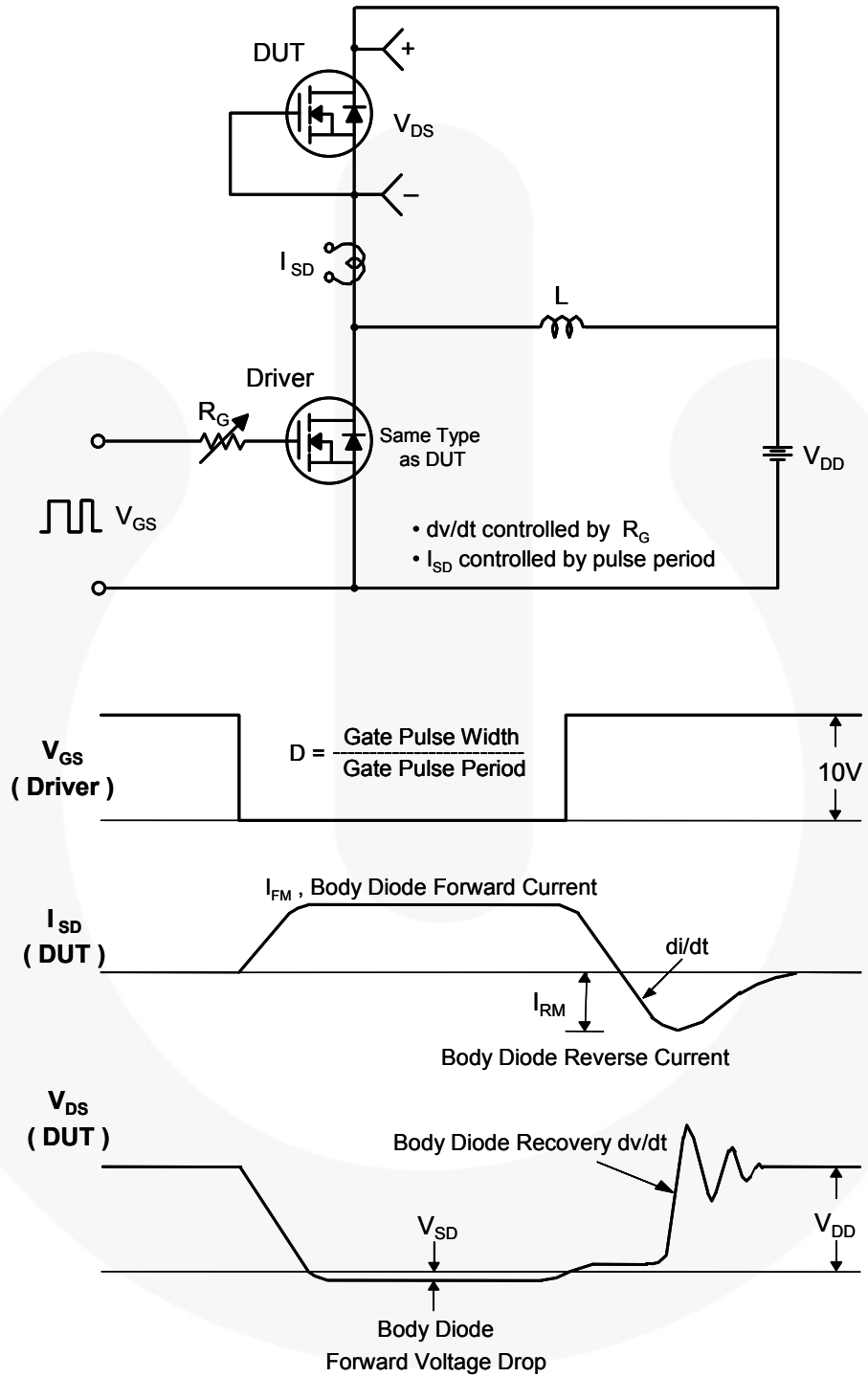
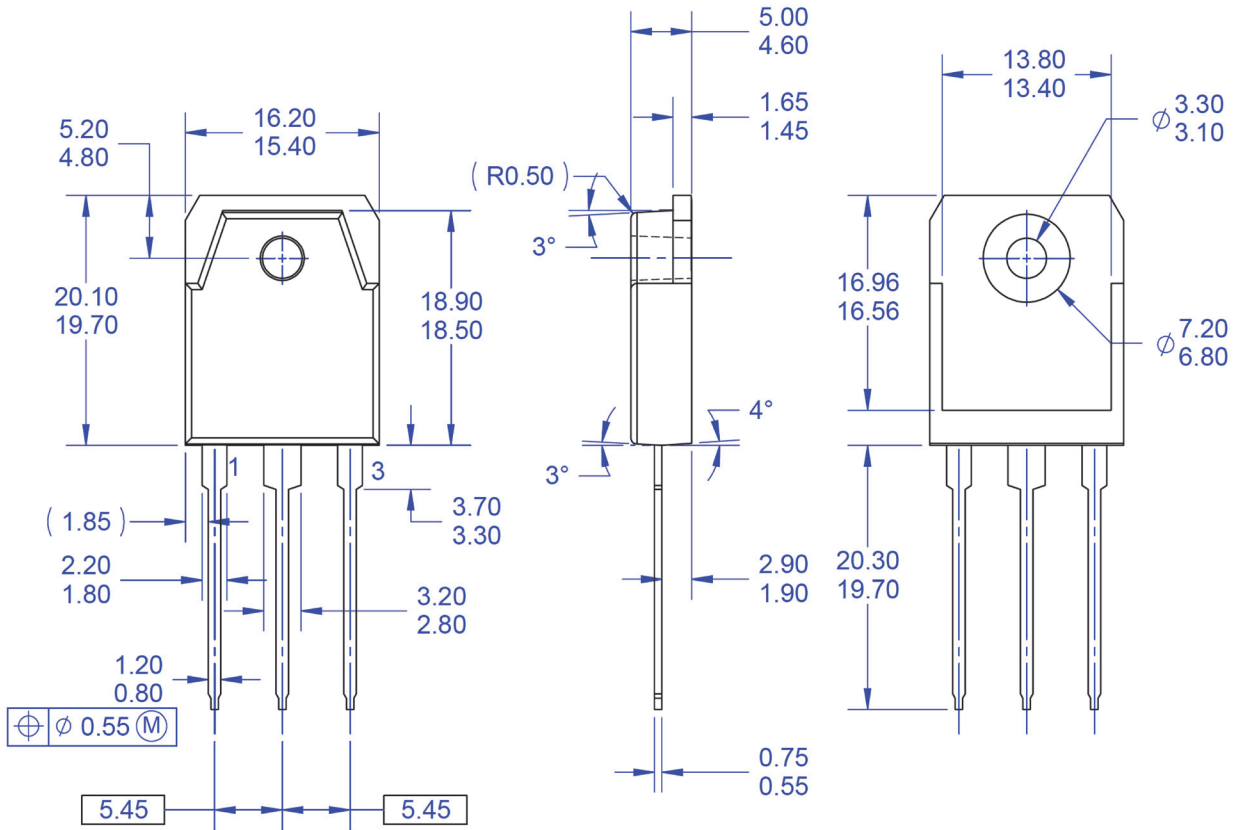


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) DRAWING FILE NAME: TO3PN03AREV1.
- F) FAIRCHILD SEMICONDUCTOR.

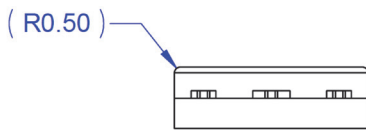


Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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